

Backside Metallization Sputtering System SRH Series

SRH Series (picture: SRH-530) is a production system for deposition of metallic films for power device, WL-CSP, or UBM or similar application.



Features

- Applicable substrate size: $\phi 125$ to 200mm.
- Capable of auto-transfer for Ultra-thin Si wafer up to 50 μ m thickness.
- Up to 5 unique process recipes.
- Sputter-Etching process developed by ISM.
- Efficient water cooling mechanism by ESC method is available.

Applications

- Power devices
- WL-CSP (seed layer of electrolytic plating)
- UBM (Barrier metal)

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